

## AMENDMENTS TO THE CLAIMS

### **1-25. (Cancelled)**

**26. (Currently Amended)** An electronic component to be mounted on a printed board, said electronic component comprising:

- an electrical connecting surface;
- ~~a plurality of electrical connecting portions~~ lands provided on said electrical connecting surface in arrangement positions within a contour of said electronic component; and
- at least one recognition mark located on a surface of the electronic component and serving as a reference for the arrangement positions of said ~~electrical connecting portions~~ lands,  
wherein said at least one recognition mark is formed on said surface simultaneously with formation of said lands on said electrical connecting surface.

**27. (Currently Amended)** The ~~An~~ electronic component as claimed in claim 26, wherein said at least one recognition mark comprises a pair of recognition marks positioned symmetrically with respect to a center point of said electrical connecting surface, wherein said ~~electrical connecting portions~~ lands are disposed in an array that surrounds said pair of recognition marks.

**28. (Currently Amended)** The ~~An~~ electronic component as claimed in claim 26, wherein said at least one recognition mark comprises plural ~~a plurality of~~ recognition marks that are positioned symmetrically with respect to a center point of said electrical connecting surface, wherein said plural recognition marks are located in a central portion of said electrical connecting surface, and said ~~electrical connecting portions~~ lands are disposed around said plural recognition marks.

**29. (Currently Amended)** The ~~An~~ electronic component as claimed in claim 26, wherein said at least one recognition mark is provided on a side of said electrical connecting surface that is adapted to confront a mounting position of the printed board.

**30. (Currently Amended)** The ~~An~~ electronic component as claimed in claim 29, wherein said at least one recognition mark comprises a projection or a printed symbol.

**31. (Currently Amended)** An electronic component to be mounted on a printed board, said electronic component comprising:

- an electrical connecting surface;
- ~~a plurality of~~ electrical connecting portions provided on said electrical connecting surface in arrangement positions; and
- at least one recognition mark located on a surface of the electronic component and serving as a reference for the arrangement positions of said electrical connecting portions,

wherein said at least one recognition mark includes coded information indicative of said electronic component.

**32. (Currently Amended)** ~~The An~~ electronic component as claimed in claim 31, wherein the coded information of said at least one recognition mark is information concerned with a state in which the electrical connecting portions are formed.

**33. (Currently Amended)** ~~The An~~ electronic component as claimed in claim 26, wherein said at least one recognition mark is located in a corner portion of an opposite side of the electronic component relative to said ~~electrical connecting portions~~ lands.

**34. (Cancelled)**

**35. (Currently Amended)** ~~The An~~ electronic component as claimed in claim 26 31, wherein said electrical connecting portions are solder bumps.

**36. (Currently Amended)** ~~The An~~ electronic component as claimed in claim 26 31, wherein said electrical connecting portions are lands.

**37-47. (Cancelled)**

**48. (Currently Amended)** ~~The An~~ electronic component as claimed in claim 26, wherein said at least one ~~the~~ recognition mark does not project from ~~the~~ said surface of the electronic

component.

**49. (New)** The electronic component as claimed in claim 26, wherein said surface is said electrical connecting surface.

**50. (New)** The electronic component as claimed in claim 49, wherein said at least one recognition mark and said lands are formed simultaneously on said electrical connecting surface by using a mask.

**51. (New)** The electronic component as claimed in claim 26, further comprising a solder bump on each of said lands.

**52. (New)** The electronic component as claimed in claim 51, wherein said at least one recognition mark comprises a pair of recognition marks positioned symmetrically with respect to a center point of said electrical connecting surface, wherein said lands are disposed in an array that surrounds said pair of recognition marks.

**53. (New)** The electronic component as claimed in claim 51, wherein said at least one recognition mark comprises plural recognition marks that are positioned symmetrically with respect to a center point of said electrical connecting surface, wherein said plural recognition marks are located in a central portion of said electrical connecting surface, and said lands are disposed around said plural recognition marks.

**54. (New)** The electronic component as claimed in claim 51, wherein said at least one recognition mark is provided on a side of said electrical connecting surface that is adapted to confront a mounting position of the printed board.

**55. (New)** The electronic component as claimed in claim 51, wherein said at least one recognition mark comprises a projection or a printed symbol.

**56. (New)** The electronic component as claimed in claim 51, wherein said at least one

recognition mark does not project from said electrical connecting surface of the electronic component.

**57. (New)** The electronic component as claimed in claim 51, wherein said surface is said electrical connecting surface.

**58. (New)** The electronic component as claimed in claim 51, wherein said at least one recognition mark and said lands are formed simultaneously on said electrical connecting surface by using a mask.